

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUA200N04S5N010	**Issued**	27. April 2022
MA#	MA005737395		
Package	PG-HSOF-5-1	**Weight***	368.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.661	0.45	0.45	4503	4503
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.13	13.14	131261	131431
wire	noble metal	gold	7440-57-5	0.040	0.01	0.01	109	109
encapsulation	inorganic material	zincoxide	1314-13-2	1.418	0.38		3843	
	miscellaneous	miscellaneous	-	5.671	1.54		15374	
	plastics	epoxy resin	-	21.266	5.77		57652	
	inorganic material	silicondioxide	60676-86-0	113.418	30.75	38.44	307477	384346
leadfinish	non noble metal	tin	7440-31-5	3.673	1.00	1.00	9957	9957
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.043	0.01		116	
	noble metal	silver	7440-22-4	0.054	0.01		145	
	non noble metal	lead	7439-92-1	2.044	0.55	0.57	5541	5802
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		77	
	non noble metal	copper	7440-50-8	28.224	7.65	7.66	76515	76615
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		387	
	non noble metal	copper	7440-50-8	142.638	38.68	38.73	386693	387196
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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